

Quality Semiconductor Manufacturing Equipment/Tools and Process Enhancement Solutions/Services for Sale

Updated on September 18, 2017 (http://www.surplushere.com)

Q'ty and Asking Price : Please inquire to info@justinbdnl.com , +1-512-660-7889 (US Mobile) or +82-10-3202-7102 (Korea Mobile)

No.	Process #1	Process #2	Maker	Model	Description	Wafer Size	Details	Condition
1	Front-End	Lithography	ASML	PAS5500/300C	DUV Stepper - Lens Unit only	8	DUV Stepper - Lens Unit, Cables and Panels only	Lens Unit, Cables only
2	Front-End	Lithography	Nikon	NSR-2205112D	i-Line Stepper, 8 inch Flat Zone Type 2(A3), 6 inch Reticle	8	i-Line Stepper, Wafer Stage Type 2 (A3), 6 inch Reticle	Power-up in Clean Room
3	Front-End	Lithography	Nikon	NSR-220518A	i-Line Stepper	N/A	i-Line Stepper	Vacuum Sealed in Wooden Crate
4	Front-End	Lithography	TEL	Clean Track ACT12	Photo Resist Coat and Develop System	12	Single Block, 2C2D1IFB	Excellent
5	Front-End	Lithography	TEL	Clean Track ACT12	Photo Resist Coat and Develop System	12	Single Block, 1C2D1IFB	Excellent
6	Front-End	Lithography	TEL	Clean Track ACT12	Photo Resist Coat and Develop System	12	Single Block, PIQ, 1C1D	Excellent
7	Front-End	Lithography	TEL	Clean Track ACT8	Photo Resist Coat and Develop System	8	DUV, Dual Block, 4C4D1IFB, Right to Left Wafer Flow, 4SUCs SMIF for, Interface for ASML PAS5500	Excellent
8	Front-End	Lithography	TEL	Clean Track ACT8	Photo Resist Coat and Develop System	8	DUV, Dual Block, 3C4D1IFB, Right to Left Wafer Flow, 4UNCs Open Cassette, Interface for ASML PAS5500	Excellent
9	Front-End	Lithography	TEL	Clean Track ACT8	Photo Resist Coat and Develop System	8	DUV, Dual Block, 3C4D1IFB, Left to Right Wafer Flow, 4UNCs Open Cassette, Interface for Canon ES3	Excellent
10	Front-End	Lithography	TEL	Clean Track ACT8	Photo Resist Coat and Develop System	8	DUV, Single Block, 2C2D1IFB, Right to Left Wafer Flow, 4UNCs Open Cassette, Interface for ASML PAS5500	Excellent
11	Front-End	Lithography	TEL	Clean Track ACT8	Photo Resist Coat and Develop System	8	DUV, Single Block, 2C2D1IFB, Left to Right Wafer Flow, 4UNCs Open Cassette, Interface for Nikon NSR-2205EX14C	Excellent
12	Front-End	Lithography	TEL	Clean Track Mark8	Photo Resist Coat and Develop System	8	Dual Block, 2C3D1IFB	Excellent
13	Front-End	Lithography	TEL	Clean Track Mark8	Photo Resist Coat and Develop System	8	Single Block, 2C2D1IFB	Excellent
14	Front-End	Lithography	TEL	Clean Track Mark8	Photo Resist Coat and Develop System	8	Single Block, 2C1D	Excellent
15	Front-End	Lithography	TEL	Clean Track Mark7	Photo Resist Develop System	8	Dual Block, 2C3D1IFB	Excellent
16	Front-End	Lithography	TEL	Clean Track Mark7	Photo Resist Develop System	8	Dual Block, 5D	Excellent
17	Front-End	Lithography	TEL	Clean Track Mark7	Photo Resist Coat and Develop System	8	Single Block, 4D	Excellent
18	Front-End	Lithography	TEL	Clean Track Mark7	Photo Resist Coat and Develop System	8	Single Block, 1SCR1C2D1IFB	Excellent
19	Front-End	Lithography	TEL	Clean Track Mark7	Photo Resist Coat and Develop System	8	Single Block, 1C2D1SCR	Parts Machine
20	Front-End	Lithography	TEL	Clean Track Mark7	Photo Resist Coat System	8	Single Block, 3C (PIQ/Polyimide Coat)	Some Parts Missing
21	Front-End	Lithography	TEL	Clean Track Mark7	Photo Resist Coat System	8	Single Block, 2C1RSV	Excellent
22	Front-End	Lithography	TEL	Clean Track Mark7	Photo Resist Develop System	8	Single Block, 3D	Excellent
23	Front-End	Lithography	TEL	Clean Track Mark 7 and Mark 8	Photo Resist Coat and Develop System	4/5/6/8	Parts, Labor, Refurbishment and Modification Service - Inch Conversion (4/5/6/8") for both Silicon Wafer and LED Sapphire Substrate - SMIF (3 SUCs or 4 SUCs) Integrated CSB Modification - Wafer Flow Modification (Left to Right or Right to Left) - Step/Scanner Interface Modification (ASML, Nikon, Canon, SVGL) - Spin Unit Modification (COT,BCT,TCT,DEV) - Oven Unit Modification (AD, HP, HHP, DHP, COL, PEB, etc.) - Interface Modification - T&H Controller Modificaiton, Repair - Chemical Supply System Modification - Thermo controller Modification - Exhaust MFC Upgrade for Advanced Process - Photo Resist Dispense Monitoring System (Fin Flow FMS for Photo Resist, Solvent, Develop and DI Water)	Refurbishment Modification Service
24	Front-End	Lithography	Justin BD&L, Inc.	LithoFlow - Multi Tracks	LithoFlow Chemical Monitoring System for Multi Tools/Machines Application with Remote Monitoring Groupware via Ethernet	N/A	1. Process Monitoring with Alarm/Warning and Interlock/Stop 2. Flow Sensor : A. FinFlow Type is available up to Viscosity 50cp (1cc/1sec) B. Micro MEMS Thermo Sensor : No limit on Viscosity 3. Multi Tools/Machines Groupware Application Customer can monitor real time based dispense condition of Photo Track at the desk A. Ethernet Connection to Laptops and Main Server via Access Point and Ethernet Hub B. MAX 250 Tools interconnected C. MAX 300 Sensors per Tool (MAX 120 Spin Units) with 15 Interface Controller Group (1 Group consists of 1 Main Controller + 1 Add-on Controller) which support Both Digital Pulse Sensor Input and Analog Sensor Input D. MAX 75,000 Sensors (MAX 250 Tools, 30,000 Spin Units) with 3,750 Interface Controller Groups E. Multi Bands Outputs : Max 3 Upper & Lower Limit "Alarm/Warning" and 1 Upper & 1 Lower Limit "Interlock/Stop" F. Multi Recipe Support (MAX 20 Recipes per Dispense Nozzle) G. Interchangeable with TEL OEM Fin Flow Sensor for TEL Clean Track ACT 8 and ACT 12 H. FDC Option Support Available 4. Available for Photo Resist, SOG/SOD, Solvent (EBR, Back Rinse, Solvent Bath, Cup Rinse, Nozzle Rinse), Develop Solutions, DIW Top Rinse, etc. 5. Available for All Photo Tracks including A. TEL Lithius, Lithius Pro B. Sokudo C. TEL Clean Track Mark 7, Mark 8, ACT 8 or ACT 12 D. DNS 60A, 60B, 80A, 80B, SK200W, SK2000. E. SVG 86, 88, 90, 90-S, 90-SE F. Tazmo SEMIX SOG Coater	New

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No.	Process #1	Process #2	Maker	Model	Description	Wafer Size	Details	Condition
25	Front-End	Lithography	Justin BD&L, Inc.	LithoFlow - Single Track	LithoFlow Chemical Monitoring System for Single Tool/Machine Application	N/A	1. Process Monitoring with Alarm/Warning and Interlock/Stop 2. Flow Sensor : A. FinFlow Type is available up to Viscosity 50cp (1cc/1sec) 3. Single Tool/Machine Application A. USB Connection to Laptop B. MAX 8 Spin Units, 32 Sensors with 4 USB Interface Controllers via 1 USB Hub (4 Ports) C. 1 Band Output : 1 Upper (Alarm/Warning or Interlock/Stop) and 1 Lower (Alarm/Warning or Interlock/Stop) Limit D. Multi Recipe Support (MAX 20 Recipes per Dispense Nozzle) E. Interchangeable with TEL OEM Fin Flow Sensor for TEL Clean Track ACT 8 and ACT 12 F. FDC Option Support Available 4. Available for Photo Resist, SOG/SOD, Solvent (EBR, Back Rinse, Solvent Bath, Cup Rinse, Nozzle Rinse), Develop Solutions, DIW Top Rinse, etc. 5. Available for All Photo Tracks including A. TEL Lithius, Lithius Pro B. Sokudo C. TEL Clean Track Mark 7, Mark 8, ACT 8 or ACT 12 D. DNS 60A, 60B, 80A, 80B, SK200W, SK2000. E. SVG 86, 88, 90, 90-S, 90-SE F. Tazmo SEMIX SOG Coater	New
26	Front-End	Lithography	DNS	80BW	Photo Resist Coat and Develop System	8	Dual Block, 1C2D1IFB	Excellent
27	Front-End	Lithography	DNS	80A	Photo Resist Coat and Develop System	8	Dual Block, 2C2D1IFB	1 Scrubber Unit Missing
28	Front-End	Lithography	DNS	SK-80BW-AVPE	Photo Resist Develop System	8	Single Block, 3D	A few Parts Missing
29	Front-End	Lithography/CVD	DNS	SC-W80A-AVFG	SOG Coat and Vertical Furnace System	8	Upgraded DNS SC-W80A-AVFG SOG Coat and Vertical Furnace with Remanufacturing Technology - 2 SOG Coat Units and 1 Vertical Furnace - Upgrade service with New Industrial Controller and Digital I/O Controller including Windows GUI scheduler software, WPH upgraded, New Spin Motor/Driver and New Servo Motor/Driver for INR & WTR Robots - Wafer Level Recipe Processing and Command - Real Time Process Log - Online Communication (SECS/GEM) Option with real time wafer & lot tracking - Inch Conversion (4/5/6/8") available for both Silicon Wafer and LED Sapphire Substrate	Upgrade Service
30	Front-End	Etch	AMAT	DPS II	Metal Etch	12	3 DPS II Metal Etch Chs, 2 Axiom Chs, Vintage 2008	Excellent
31	Front-End	Etch	AMAT	Centura 5200	WxP Chamber (Mechanical Clamp Chuck)	8	WxP Chamber (Mechanical Clamp Chuck)	Good
32	Front-End	Etch	AMAT	Centura or Centura II DPS	Chamber, Lower, DPS (0021-09625)	8	Chamber, Lower, DPS (0021-09625)	New, 2nd Source
33	Front-End	Etch	AMAT	Centura or Centura II DPS	Chamber Body, ASP+ (0040-32136)	8	Chamber Body, ASP+ (0040-32136)	New, 2nd Source
34	Front-End	Etch	AMAT	Centura or Centura II	Orient Chamber	8	Orient Chamber	New, 2nd Source
35	Front-End	Etch	Lam Research	Rainbow 4526	Oxide Etch	6	Hine 38A Indexer, Clamp, Classic SW, AE PDW2200 RFG	A few Parts Missing
36	Front-End	Etch	Lam Research	Rainbow 4428	Poly/Nitride Etch	8	Hine 38A Indexer, Clamp, Classic SW, ENI OEM650 RFG	Excellent
37	Front-End	Ash	Novellus-Gasonics-IPC	A3010	Dry Ash	8	Single Chamber Dry Asher	Operational
38	Front-End	CVD	AMAT	P5000	SA BPSG	8	3 SA BPSG Chambers (TEOS)	Good
39	Front-End	Ion Implant	Axcelis-Eaton	GSD100	Gyro Disk for GSD100	8	Gyro Disk for GSD100	Overhauled
40	Front-End	Clean	DNS	SS-W80-AR	Wafer Spin Scrubbing/Cleaning	8	Upgraded DNS SS-W80A-AR Wafer Spin Scrubber with Remanufacturing Technology - Upgrade service with New Industrial Controller and Digital I/O Controller including Windows GUI scheduler software, WPH upgraded, New Spin Motor/Driver and New Servo Motor/Driver for INR & WTR Robots - Wafer Level Recipe Processing and Command - Real Time Process Log - Online Communication (SECS/GEM) Option with real time wafer & lot tracking with - Inch Conversion (4/5/6/8") for both Silicon Wafer and LED Sapphire Substrate - Spin Scrubbing Method Modification (High Pressure Jet, D-Sonic, Nanospray) - Spin Unit Modification (Front Side, Back Side, Double Sides) - Wafer Flow Modification (Left to Right or Right to Left) Note : HF, NH4OH, SC1 or SC2 Chemical Scrubbing Modification is available	Upgrade Service
41	Front-End	Clean	DNS	SS-W80-AR	Wafer Spin Scrubbing/Cleaning	8	Throughput(WPH) Upgraded, New SW/Controller 3 Front, 3 Back Side Scrubbing Units w/ Nanospray HF, NH4OH, SC1 or SC2 Chemical Scrubbing is also available.	Remanufactured/Upgraded Operational
42	Front-End	Clean	DNS	SS-W80A-AR	Wafer Spin Scrubbing/Cleaning	8	2 Front, 2 Back Side Scrubbing Units w/ Nanospray	Excellent
43	Front-End	Clean	DNS	SS-W80A-AR	Wafer Spin Scrubbing/Cleaning	8	2 Front, 2 Back Side Scrubbing Units w/ High Pressure Jet	Excellent
44	Front-End	Clean	DNS	SS-W80A-AR	Wafer Spin Scrubbing/Cleaning	8	4 Back Side Scrubbing Units w/ High Pressure Jet	Excellent
45	Front-End	Clean	DNS	SS-W80A-AR	Wafer Spin Scrubbing/Cleaning	8	4 Front Side Scrubbing Units w/ High Pressure Jet	Excellent

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46	Front-End	Clean	DNS	SS-W80A-AR	Wafer Spin Scrubbing/Cleaning	8	4 Front Side Scrubbing Units w/ Nanospray	Excellent
47	Front-End	Metrology	Hitachi	S8820HSA	CDSEM	8	CDSEM	Excellent
48	Front-End	Metrology	Nicolet	ECO-1000S	FT-IR	8	FT-IR	Controller Missing
49	Front-End	Metrology	SDI	SPV-1050	Contamination Monitoring System	8	Contamination Monitoring System	Excellent
50	Front-End	Others	Asyst	Spartan	EFEM Wafer Sorter	12	2 FOUP, 300mm EFEM Wafer Sorter	Excellent
51	Front-End	Others	Asyst	PST100	Wafer Sorter	8	SMIF, WMS/Wafer Metrology Sorter (2SMIF Indexers)	Upgraded, Operational
52	Front-End	Others	Axcelis-Fusion	GPS	Dual Chamber UV Stabilizer/Bake	8	Dual Chamber UV Stabilizer/Bake with 3 Axis Robot	Some Parts Missing
53	Front-End	Others	Axcelis-Fusion	200PCU	UV Stabilizer/Bake	8	Single Chamber UV Stabilizer/Bake with 3 Axis Robot, SMIF	Power-up, Initialized
54	Front-End	Others	Axcelis-Fusion	200PCU	UV Stabilizer/Bake	8	Single Chamber UV Stabilizer/Bake with 3 Axis Robot	Excellent
55	Front-End	RTP	Mattson	AST3000	RTP	8	Single Chamber RTP with 3 Load/unloaders	Power-up, Initialized
56	Front-End	RTP	Mattson	AST2900	RTP	8	Single Chamber RTP with 2 Load/unloaders	Power-up, Initialized
57	Front-End	RTP	Mattson	AST2800	RTP	8	Single Chamber RTP with 2 Load/unloaders	Excellent
58	ATE	EDS	TEL	TEL Chiller for TEL P-12XL Cold	TEL D230 / ADA-K5 Chiller for TEL P-12XL Cold Prober (300mm, 12")	12	Cold Chuck with Manipulator, Chiller (TEL D230/ADA-K5)	Power-up
59	ATE	SSM	SSM	5200	SSM/Solid State Measurement 5200 CV-Plotter System	8	SSM/Solid State Measurement 5200 CV-Plotter System	Fare
60	ATE	EDS	ESI	9275	Laser Repair System - Modules and Parts only	8	Laser Repair System - Modules and Parts only	Modules and Parts only
61	Back-End	Saw	Disco	N/A	Heavy Smoker for Disco Dicing Saw DFD6361	N/A	Heavy Smoker for Disco Dicing Saw DFD6361, Vintage 2006	Power-up, Initialized
62	Back-End	Saw	NGK	Maggon II, RCII-2000ACD-S	CO2 Bubbler, NGK Maggon II, RCII-2000ACD-S for DFD6361	N/A	CO2 Bubbler, NGK Maggon II, RCII-2000ACD-S for DFD6361, Vintage 2006	Power-up, Initialized
63	Back-End	Saw	Disco	DSC141	After Sawing Cleaner - Spin/Rinse/Dryer	8	Automatic Spin/Rinse/Drying System after Sawing, Vintage 2006	Power-up, Initialized
64	Back-End	Detape	Lintec	RAD2000/F8	UV Irradiator for Detaping System	8	Automatic UV Irradiator for Detaping System	Good
65	Back-End	Tape	Nitto	DR8500II	Automatic Taper	8	Automatic Laminator/Taper	Some Parts Missing
66	Back-End	Detape	Nitto	HR8500II	Automatic Detaper, Tape Remover	8	Automatic Detaping System, Detaper, Tape Remover with UV Module	Power-up, Initialized
67	Back-End	Detape	Nitto	HR8500II	Automatic Detaper, Tape Remover	8	Automatic Detaping System, Detaper, Tape Remover without UV Module	NEL Touch Panel missing
68	Back-End	Detape	Takatori	ATM8100	Automatic Detaper, Tape Remover	8	Automatic Laminator/Taper	Good
69	Back-End	Detape	Takatori	ATRM2100	Automatic Detaper, Tape Remover	8	Automatic Detaping System, Detaper, Tape Remover	Excellent
70	Auxiliary	Pump	Edwards	iH600	Dry Pump	N/A	Dry Pump	
71	Auxiliary	Pump	Edwards	iH80	Dry Pump	N/A	Dry Pump	
72	Auxiliary	Pump	Edwards	iGX100M	Dry Pump	N/A	Dry Pump	
73	Auxiliary	Pump	Edwards	iQDP80 + QMB500	Dry Pump and Roughing Pump	N/A	Dry Pump and Roughing Pump	
74	Auxiliary	Pump	Edwards	QDP80 + QMB500	Dry Pump and Roughing Pump	N/A	Dry Pump and Roughing Pump	
75	Auxiliary	Pump	Edwards	iQDP80 + QMB250	Dry Pump and Roughing Pump	N/A	Dry Pump and Roughing Pump	
76	Auxiliary	Pump	Edwards	iQDP80	Dry Pump	N/A	Dry Pump	
77	Auxiliary	Pump	Edwards	QDP80	Dry Pump	N/A	Dry Pump	
78	Auxiliary	Pump	Edwards	iQDP40	Dry Pump	N/A	Dry Pump	
79	Auxiliary	Pump	Edwards	QDP40	Dry Pump	N/A	Dry Pump	
80	Auxiliary	Pump	Ebara	A150W-T	Dry Pump	N/A	Dry Pump	
81	Auxiliary	Pump	Ebara	A70W	Dry Pump	N/A	Dry Pump	
82	Auxiliary	Pump	Ebara	A30W	Dry Pump	N/A	Dry Pump	
83	Auxiliary	Pump	Ebara	80 x 25	Dry Pump and Roughing Pump	N/A	Dry Pump and Roughing Pump	
84	Auxiliary	Pump	Ebara	40 x 20	Dry Pump and Roughing Pump	N/A	Dry Pump and Roughing Pump	
85	Auxiliary	Pump	Alcatel	ADS501	Dry Pump	N/A	Dry Pump	
86	Auxiliary	Pump	Leybold	WSU501	Dry Pump	N/A	Dry Pump	
87	Auxiliary	Pump	Kashiyama	SD90V	Pump	N/A	Pump	
88	Auxiliary	TMP	Edwards - Seiko-Seiki	Various	TMP/Turbo Modular Pump	N/A	TMP/Turbo Modular Pump	
89	Auxiliary	TMP Controller	Edwards - Seiko-Seiki	Various	TMP/Turbo Modular Pump Controller	N/A	TMP/Turbo Modular Pump Controller	
90	Auxiliary	Compressor	CTI	9600	Cryo Compressor	N/A	Cryo Compressor, S/N E08754276, Elapsed Time Meter 3,371.1H, Gas He Charge Pressure at On/Off Condition is all within Specification	Operational
91	Auxiliary	Compressor	CTI	9600	Cryo Compressor	N/A	Cryo Compressor, S/N D06456510, Elapsed Time Meter 23,877.9H, Gas He Charge Pressure at On/Off Condition is all within Specification	Operational
92	Auxiliary	Compressor	CTI	9600	Cryo Compressor	N/A	Cryo Compressor, S/N J02119034, Elapsed Time Meter 50,028.4H, Gas He Charge Pressure at On/Off Condition is all within Specification	Operational
93	Auxiliary	Compressor	CTI	9600	Cryo Compressor	N/A	Cryo Compressor, S/N K02119255, Elapsed Time Meter 50,030.8H, Gas He Charge Pressure at On/Off Condition is all within Specification	Operational
94	Auxiliary	Compressor	CTI	8510	Cryo Compressor	N/A	Cryo Compressor	
95	Auxiliary	Compressor	CTI	8500	Cryo Compressor	N/A	Cryo Compressor	
96	Auxiliary	RF Generator	ENI	Various	RF Generator or RF Power Supply	N/A	RF Generator or RF Power Supply	
97	Auxiliary	RF Generator	AE/Advanced Energy	Various	RF Generator or RF Power Supply	N/A	RF Generator or RF Power Supply	
98	Auxiliary	RF Generator	Daihen	Various	RF Generator or RF Power Supply	N/A	RF Generator or RF Power Supply	
99	Auxiliary	RF Generator	Adtec	Various	RF Generator or RF Power Supply	N/A	RF Generator or RF Power Supply	
100	Auxiliary	RF Match	AE/Advanced Energy	Various	RF Match	N/A	RF Match	
101	Auxiliary	RF Match	Daihen	Various	RF Match	N/A	RF Match	
102	Auxiliary	RF Match	Daihen	Various	RF Match	N/A	RF Match	



Justin BD&L

Business Development & Licensing

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Advanced Solutions Provider for Semiconductor and LED Manufacturing Equipment
+ Windows GUI Scheduler Software Solutions for Semiconductor Manufacturing Equipment
+ Process Monitoring and Performance Enhancement Products and Solutions
+ Used and Refurbished Equipment for Sale
+ Refurbishment, Modification, Engineering and Labor Service



Registered ISO 14001:2004



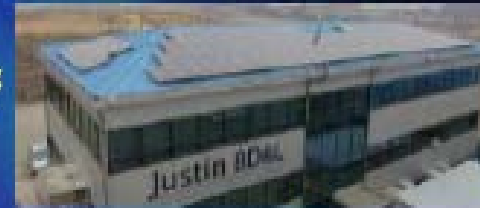
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INNOBIZ
기술혁신형중소기업

Clean Room Facility I

- The State of the Art Clean Room Facility for Quality Refurbishment Service in New Dongtan II City
5min driving distance from Samsung FABs, 30min from Seoul and 90min from Incheon International Airport
Main Building Size : 1,676.03m² / 18,040.23ft² / 507pyung
Clean Room (Class 100) Size : 552.68m² / 6,013.41ft² / 169pyung
Clean Room (Class 1,000) Size : 2,079.35m² / 22,391.14ft² / 629pyung
- All Clean Rooms have DI Water, PCW, CDA, Power (480kW, 220VAC)
- On-site Solar Power Generation Systems installed for Green Energy



Clean Room Facility II

- 2nd Facility (3 Floors) completed in Mar 2007 (2,622.76 m² / 28,230.89 ft² / 793pyung)
- 5min driving distance from Samsung FABs, 30min from Seoul and 90min from Incheon International Airport
- The State of the Art Clean Room Facility for the Quality Refurbishment Service of
200mm (8"), 300mm (12") and 450mm (18") Wafer FAB Tools
- All Clean Rooms have DI Water, PCW, CDA, Power (480kW, 220VAC)
- On-site Solar Power Generation Systems installed for Green Energy

